

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT7614760

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EBRAHIM MOLAVIANJAZI	09/25/2018
VIJAY NANGIA	09/25/2018
HYEJUNG JUNG	09/25/2018
COLIN D. FRANK	09/25/2018
ROBERT T. LOVE	09/25/2018
RAVI KUCHIBHOTLA	09/25/2018
HOSSEIN BAGHERI	09/24/2018
RECEIVING PARTY DATA	
Name:	LENOVO (SINGAPORE) PTE. LTD.
Street Address:	151 LORONG CHUAN
Internal Address:	# 02-01
City:	NEW TECH PARK
State/Country:	SINGAPORE
Postal Code:	556741
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17883431
CORRESPONDENCE DATA	
Fax Number:	(801)531-1929
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	8019944646
Email:	dhuynh@kba.law
Correspondent Name:	BRIAN C. KUNZLER
Address Line 1:	50 WEST BROADWAY, 10TH FLOOR
Address Line 4:	SALT LAKE CITY, UTAH 84101
ATTORNEY DOCKET NUMBER:	SMM920170036-US-C1-CNT2
NAME OF SUBMITTER:	DIANA HUYNH
SIGNATURE:	/DIANA HUYNH/

DATE SIGNED:	10/27/2022
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Total Attachments: 8

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **Ebrahim MolavianJazi, Lincolnwood, Illinois; Vijay Nangia, Woodridge, Illinois; Hyejung Jung, Palatine, Illinois; Colin D. Frank, Park Ridge, Illinois; Robert T. Love, Barrington, Illinois; Ravi Kuchibhotla, Clarendon Hills, Illinois; and Hossein Bagheri, Urbana, Illinois;** have sold, assigned and transferred, and do hereby sell, assign and transfer, unto **Lenovo (Singapore) Pte. Ltd.**, a corporation of Singapore, having a place of business at 151, Lorong Chuan #02-01, New Tech Park, Singapore 556741, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions entitled **"UPLINK POWER CONTROL"** as described, illustrated in **SMM920170036-US-NP** and as described, illustrated and claimed in the following applications:

U.S. Application filed herein and entitled: **"UPLINK POWER CONTROL"**

I hereby also sell, assign and transfer unto Assignee, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and I further authorize Assignee to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby also sell, assign and transfer unto Assignee, the entire right, title and interest in and to other applications for Letters Patent on the inventions referenced in this Assignment and Agreement, and all rights, title and interest in and to all applications for Letters Patent in respect of the invention filed under any and all international conventions and treaties together with the entire right, title and interest in and to Letters Patent which may be issued upon the application(s) or any application(s) otherwise claiming priority thereto, and upon any divisions, extensions, continuations, reissues and/or re-examinations of such application(s).

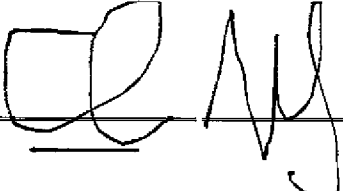
I further authorize Assignee to apply for Letters Patent directly in its own name where applicable, and to claim priority of the filing date of the application for Letters Patent filed under the laws of the applicable country and under the provisions of any and all international conventions and treaties.

I hereby authorize Assignee to request the Commissioner of Patents of the United States of America to issue any Letters Patents upon the aforesaid application, divisions, extensions, continuations, reissues or re-examinations, to Assignee, for the sole use and benefit of Assignee, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize Assignee to request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

I agree that, when requested, I will, without charge to Assignee, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing, maintaining and enforcing patents for the inventions in any and all countries and for vesting title thereto in Assignee.

I covenant with Assignee that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **Ebrahim MolavianJazi**

Signature:  Date: 09/25/2018

(2) Legal Name of Inventor: **Vijay Nangia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Hyejung Jung**

Signature: _____ Date: _____

I hereby authorize Assignee to request the Commissioner of Patents of the United States of America to issue any Letters Patents upon the aforesaid application, divisions, extensions, continuations, reissues or re-examinations, to Assignee, for the sole use and benefit of Assignee, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize Assignee to request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

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(1) Legal Name of Inventor: **Ebrahim MolavianJazi**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Vijay Nangia**

Signature:  Date: 09/25/2018

(3) Legal Name of Inventor: **Hyejung Jung**

Signature: _____ Date: _____

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I covenant with Assignee that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **Ebrahim MolavianJazi**

Signature: _____ Date: _____

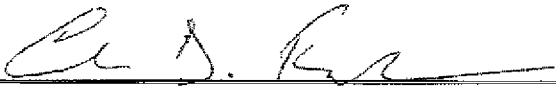
(2) Legal Name of Inventor: **Vijay Nangia**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Hyejung Jung**

Signature:  _____ Date: 9/25/2018

(4) Legal Name of Inventor: **Colin D. Frank**

Signature:  Date: Sept 25, 2018

(5) Legal Name of Inventor: **Robert T. Love**

Signature: _____ Date: _____

(6) Legal Name of Inventor: **Ravi Kuchibhotla**

Signature: _____ Date: _____

(7) Legal Name of Inventor: **Hossein Bagheri**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Colin D. Frank**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Robert T. Love**

Signature: Robert T Love Date: 9/25/2018

(6) Legal Name of Inventor: **Ravi Kuchibhotla**

Signature: _____ Date: _____

(7) Legal Name of Inventor: **Hossein Bagheri**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Colin D. Frank**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Robert T. Love**

Signature: _____ Date: _____

(6) Legal Name of Inventor: **Ravi Kuchibhotla**

Signature:  _____ Date: September 25, 2018

(7) Legal Name of Inventor: **Hossein Bagheri**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Colin D. Frank**

Signature: _____ Date: _____

(5) Legal Name of Inventor: **Robert T. Love**

Signature: _____ Date: _____

(6) Legal Name of Inventor: **Ravi Kuchibhotla**

Signature: _____ Date: _____

(7) Legal Name of Inventor: **Hossein Bagheri**

Signature: *Hossein Bagheri* Date: september 24, 2018